ROHM

# **DTC144E** series

NPN 100mA 50V Digital Transistor (Bias Resistor Built-in Transistor)

Parameter	Value	
V <sub>CC</sub>	50V	
I <sub>C(MAX.)</sub>	100mA	
R <sub>1</sub>	47kΩ	
R <sub>2</sub>	47kΩ	

## Features

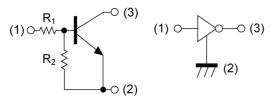
- 1) Built-In Biasing Resistors,  $R_1 = R_2 = 47k\Omega$
- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary PNP Types: DTA144E series

## Application

INVERTER, INTERFACE, DRIVER

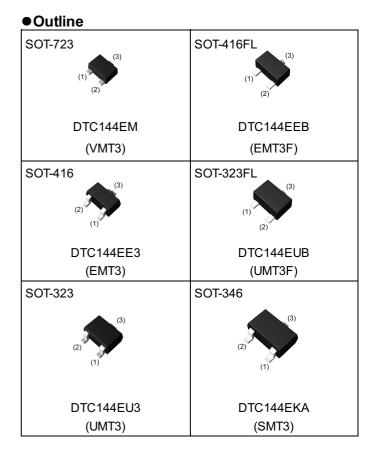
## Inner circuit

DTC144EM/ DTC144EEB/ DTC144EUB

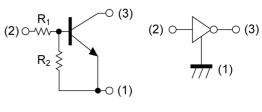


(1) IN (BASE)(2) GND (EMITTER)(3) OUT (COLLECTOR)

## Packaging specifications



# DTC144EE3/ DTC144EU3/ DTC144EKA



(1) GND (EMITTER)
(2) IN (BASE)
(3) OUT (COLLECTOR)

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Quantity (pcs)	Marking
DTC144EM	SOT-723	1212	T2L	180	8	8000	26
DTC144EEB	SOT-416FL	1616	TL	180	8	3000	26
DTC144EE3	SOT-416	1616	TL	180	8	3000	26
DTC144EUB	SOT-323FL	2021	TL	180	8	3000	26
DTC144EU3	SOT-323	2021	T106	180	8	3000	26
DTC144EKA	SOT-346	2928	T146	180	8	3000	26

## • Absolute maximum ratings (T<sub>a</sub> = 25°C)

F	Symbol	Values	Unit	
Supply voltage	V <sub>CC</sub>	50	V	
Input voltage		V <sub>IN</sub>	-10 to 40	V
Output current		Ι <sub>ο</sub>	30	mA
Collector current			100	mA
	DTC144EM		150	
	DTC144EEB		150	
Dower discipation	DTC144EE3		150	ma)///
Power dissipation	DTC144EUB	г <sub>D</sub> -	200	— mW
	DTC144EU3		200	
	DTC144EKA		200	
Junction temperature		Tj	150	°C
Range of storage tempera	ature	T <sub>stg</sub>	-55 to +150	°C

## • Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currents al	Conditions	Values			1 1
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
	V <sub>I(off)</sub>			0.5		
Input voltage	V <sub>I(on)</sub>			-	-	V
Output voltage	V <sub>O(on)</sub>	I <sub>O</sub> = 10mA, I <sub>I</sub> = 0.5mA	-	100	300	mV
Input current	I <sub>I</sub>	V <sub>1</sub> = 5V	-	-	180	μA
Output current	I <sub>O(off)</sub>	$V_{CC} = 50V, V_{I} = 0V$	-	-	500	nA
DC current gain	G <sub>I</sub>	V <sub>O</sub> = 5V, I <sub>O</sub> = 5mA	68	-	-	-
Input resistance	R <sub>1</sub>	-	32.9	47	61.1	kΩ
Resistance ratio	R <sub>2</sub> /R <sub>1</sub>	-	0.8	1.0	1.2	-
Transition frequency	f <sub>T</sub> *1	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz	-	250	-	MHz

\*1 Characteristics of built-in transistor

\*2 Each terminal mounted on a reference land.





100

30

20

10

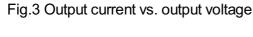
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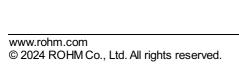
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OUTPUT CURRENT : Io [mA]

Ta = 25°C

Puls





2

4

6

OUTPUT VOLTAGE : Vo [V]

8

60µA

50µA

40µA

30µA

0A

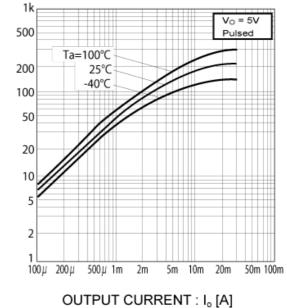
10

2.5

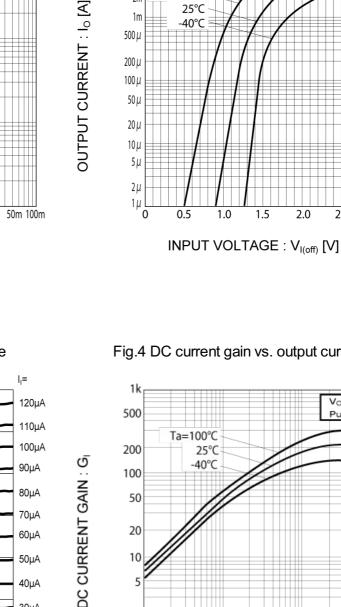
3.0

Fig.2 Output current vs. input voltage (OFF characteristics)

Fig.4 DC current gain vs. output current



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10m

5m

2m

1m

500 µ

200 µ

100 µ

50 µ

 $V_0 = 0.3V$ 

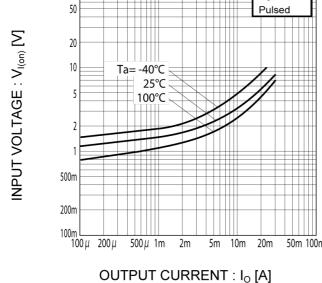
 $V_{CC} = 5V$ 

Ta=100°C

25°C

-40°C

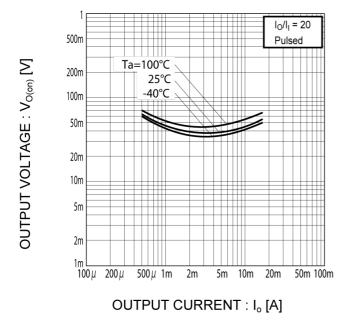
Pulsed

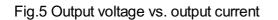


●Electrical characteristic curves (T<sub>a</sub> =25°C)



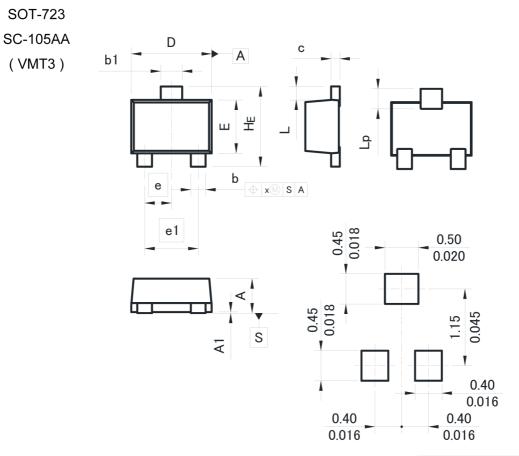
# ●Electrical characteristic curves (T<sub>a</sub> =25°C)











Soldering footprint Unit: (mm inches)

DIM	Millimeters		Incl	nes
	Min.	Max.	Min.	Max.
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.4	40	0.016	
e1	3.0	30	0.031	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
Х	_	0.10	_	0.004

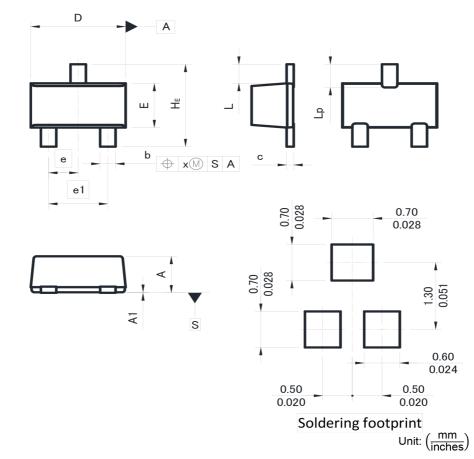




SOT-416FL

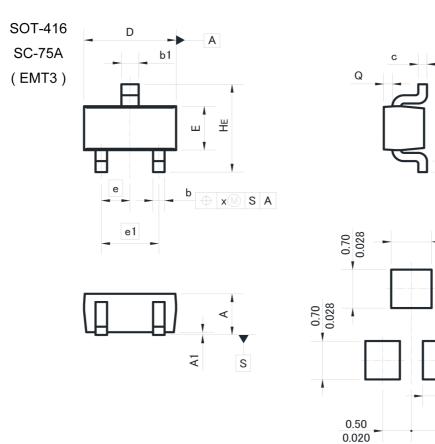
SC-89

(EMT3F)



DIM	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
A	0.60	0.90	0.024	0.035
A1	0.00	0.10	0.000	0.004
b	0.21	0.36	0.008	0.014
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.5	50	0.020	
e1	0.90	1.10	0.035	0.043
HE	1.50	1.70	0.059	0.067
L	0.37		0.0	15
Lp	0.35	0.55	0.014	0.022
Х	-	0.10	-	0.004





Soldering footprint Unit: (mm inches)

0.70 0.028

1.30

Y.

0.60 0.024

0.50

0.020

DIM	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
Α	0.60	0.90	0.024	0.035
A1	0.00	0.10	0.000	0.004
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.5	50	0.020	
e1	1.(	00	0.0	39
HE	1.40	1.80	0.055	0.071
L	0.10	-	0.004	-
Q	0.05	0.25	0.002	0.010
X	-	0.10	-	0.004

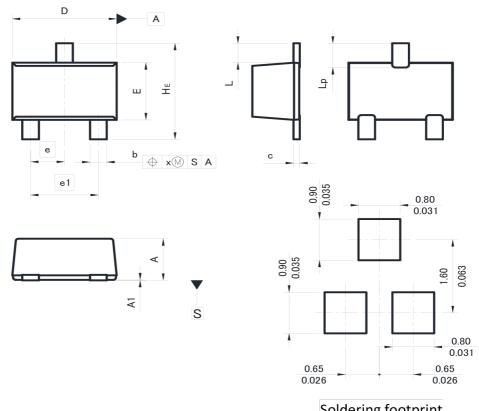




SOT-323FL

SC-85

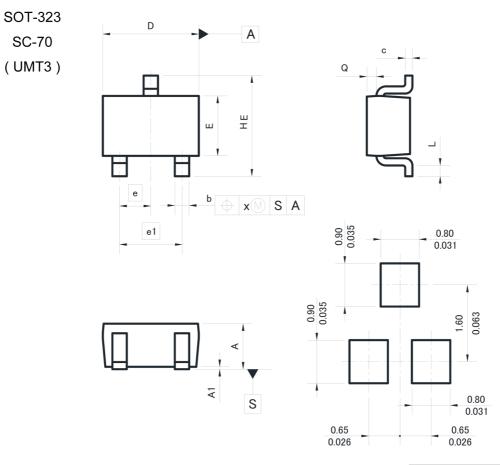
(UMT3F)



Soldering footprint Unit:  $\binom{mm}{inches}$ 

DIM	Millim	neters	Inc	hes	
	Min.	Max.	Min.	Max.	
Α	0.80	1.10	0.031	0.043	
A1	0.00	0.10	0.000	0.004	
b	0.27	0.42	0.011	0.017	
С	0.08	0.18	0.003	0.007	
D	1.90	2.10	0.075	0.083	
E	1.15	1.35	0.045	0.053	
е	0.0	65	0.026		
e1	1.20	1.40	0.047	0.055	
HE	2.00	2.20	0.079	0.087	
L	0.43		0.0	17	
Lp	0.43	0.63	0.017	0.025	
X	_	0.10	-	0.004	



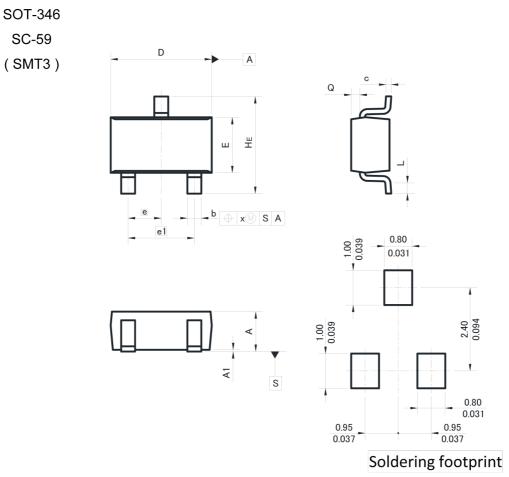


Soldering footprint Unit:  $\binom{mm}{inches}$ 

DIM	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
A	0.80	1.10	0.031	0.043
A1	0.00	0.10	0.000	0.004
b	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.6	65	0.026	
e1	1.3	30	0.0	51
HE	2.00	2.20	0.079	0.087
L	0.10	-	0.004	-
Q	0.10	0.30	0.004	0.012
х	_	0.10	_	0.004







Unit:  $\left(\frac{mm}{inches}\right)$ 

DIM	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
A	1.00	1.40	0.039	0.055
A1	0.00	0.10	0.000	0.004
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
e1	1.9	90	0.075	
HE	2.60	3.00	0.102	0.118
L	0.30	0.60	0.012	0.024
Q	0.20	0.50	0.008	0.020
х	_	0.10	-	0.004



# Notice

#### Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (<sup>Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

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